TI IBIS-AMI Model Request Process

To request an IBIS-AMI model, please send an e-mail to $\frac{highspeed\ models@list.ti.com}{highspeed\ models@list.ti.com}$. Please include the following information to ensure a timely response.

Include in e-mail	Example		
Requestor name	John Smith		
Requestor e-mail	John.Smith@AcmeNetworks.com		
Company name	Acme Networks, Inc.		
Device name of the model you are requesting	<fill device="" here="" in="" number=""></fill>		
Project details: Describe how you will use the model.	For simulating a 10G application between an ASIC and host port across a backplane including two connectors and 20 inches of total PCB trace.		

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